

Title (en)

METHOD AND DEVICE FOR PRODUCING A WAFER FROM A SEMICONDUCTING MATERIAL

Title (de)

VERFAHREN UND VORRICHTUNG ZUM HERSTELLEN EINER SCHEIBE AUS HALBLEITENDEM MATERIAL

Title (fr)

PROCEDE ET DISPOSITIF POUR LA FABRICATION D'UNE TRANCHE EN MATERIAU SEMI-CONDUCTEUR

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Application

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Abstract (en)

[origin: DE19742653A1] The invention relates to a method for producing a wafer from a semiconducting material, especially a silicon wafer, for a solar cell. According to the inventive method, a melt of the semiconducting material (8) sets to form the wafer. The invention is characterised in that said melt is exposed to an electric and/or magnetic field at least during the start of the setting process.

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